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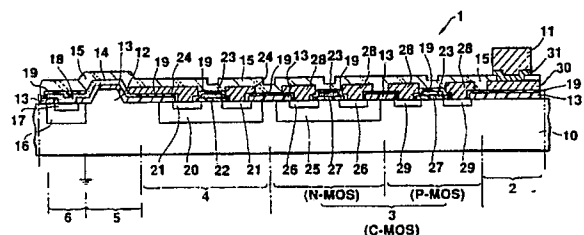
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Thermal print head and a method for manufacturing the same.

Disclosed is a thermal print head (1) in which heating resistance elements (14) are arranged with high density. The thermal print head comprises a head substrate (10), formed of a single-crystal silicon wafer, and a print driver circuit element (3, 4). The print driver circuit element (3, 4), which is formed by doping the head substrate (10) directly with an impurity, is composed of an MOS-FET. A FET used to form the single-crystal silicon substrate (10) has high electrical mobility, and serves to improve the operating speed of the thermal print head (1). Each heating resistance element (14), whose base material is polycrystalline silicon, is adjusted to a predetermined resistance value by being subjected to diffusion of an impurity. The resistance elements (14) are formed on a protuberance (12) which is formed on the head substrate (10). Thus, the portion of an insulating protective film (15) which corresponds to

the protuberance (12) projects outward from the rest, thereby ensuring contact with a printing sheet. An earthing diode (16, 17) or laminate structure is used for an earth line of each heating resistance elements (14) so that the resistance element (14) is situated close to a side edge portion of the head substrate (10).





DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int. Cl.5)
X	EP-A-129914 (TELETYPE CORP.) * abstract; figure 2 * ---	1	H01L49/02 B41J2/335
A	US-A-4429321 (CANON K.K.) * abstract; figure 1 * -----	1	
			TECHNICAL FIELDS SEARCHED (Int. Cl.5)
			H01L B41J
The present search report has been drawn up for all claims			
Place of search THE HAGUE		Date of completion of the search 23 AUGUST 1990	Examiner PELSERS L.
CATEGORY OF CITED DOCUMENTS			
X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document		T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application I : document cited for other reasons & : member of the same patent family, corresponding document	